

Art Unit: 2829

10/070,833

SD

11/10/04

1. (Currently Amended) A process for manufacturing a card with multiple tips ~~designed in particular for testing semi-conductor chips having connection pads in the form of microspheres~~, said card comprising a substrate (10) formed by a flexible insulating film equipped with conducting tracks connected to contacts in the form of tips (26), wherein:

- a first adhesive metal layer (20) of small thickness is deposited on the flexible film made of insulating material,
- a second metal layer (22) is deposited by vacuum or electrolysis on the first adhesive layer (20) to form the material of the future conducting tracks,
- the metal tips (26) are achieved by a combination of a first UV photolithography operation making use of a thick photosensitive resin and electroforming by means of a metal-ion electrolyte,
- selective etching of the second metal layer (22) and of the first adhesive layer (20) is performed by means of a second UV photolithography operation to obtain the conducting tracks,
- and a superficial passivation insulating layer (24) is deposited on the ~~active~~ conducting area-conducting tracks.

2. (Original) The process for manufacturing a card with tips according to claim 1, wherein the flexible film of the substrate (10) is a polymer, in particular a polyimide, having a thickness greater than 25 microns.

3. (Original) The process for manufacturing a card with tips according to claim 1, wherein the first adhesive metal layer (20) is chrome- or nickel-based.

4. (Original) The process for manufacturing a card with tips according to claim 1, wherein the second metal layer (22) can be made of copper, gold or aluminium.

5. (Original) The process for manufacturing a card with tips according to claim 1, wherein the tips (26) obtained by electroforming present flat, concave or convex contact surfaces.

Claims 6 through 14 are cancelled